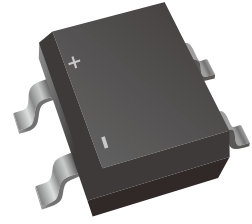


2A Surface Mount Schottky Bridge

Features

- Reverse Voltage - 40 to 200 V
- Forward Current - 2 A
- High Surge Current Capability
- Designed for Surface Mount Application



Mechanical Data

- Case: MBS(MB)
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 100mg / 0.0035oz

Maximum Ratings and Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	LTM24B	LTM26B	LTM28B	LTM210B	LTM220B	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	40	60	80	100	200	V
Maximum RMS voltage	V_{RMS}	28	42	56	70	140	V
Maximum DC Blocking Voltage	V_{DC}	40	60	80	100	200	V
Maximum Average Forward Rectified Current at $T_c = 100^\circ\text{C}$	$I_{F(AV)}$	2.0					A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	50		40			A
Max Instantaneous Forward Voltage at 2 A	V_F	0.55	0.70	0.85			V
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Reverse Voltage $T_a = 100^\circ\text{C}$	I_R	0.5 10			0.3 5		mA
Typical Junction Capacitance ¹⁾	C_j	220	80				pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	75					$^\circ\text{C/W}$
Operating Junction Temperature Range	T_j	-55 ~ +150					$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 ~ +150					$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

Ratings and characteristics Curves

Fig.1 Forward Current Derating Curve

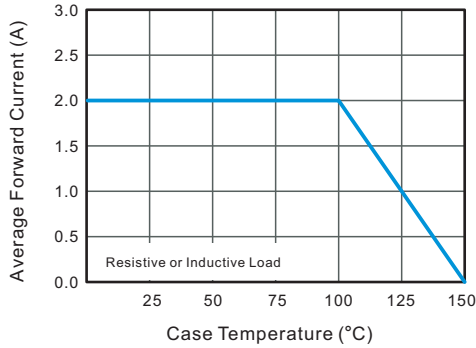


Fig.2 Typical Reverse Characteristics

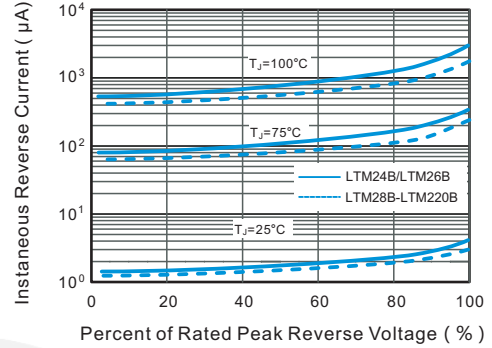


Fig.3 Typical Forward Characteristic

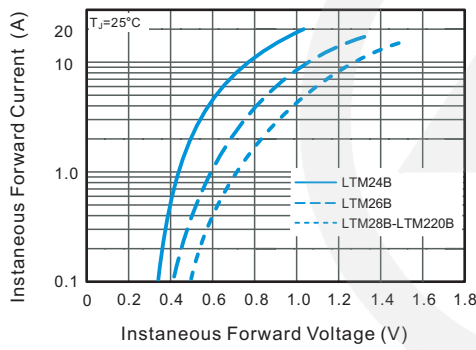


Fig.4 Typical Junction Capacitance

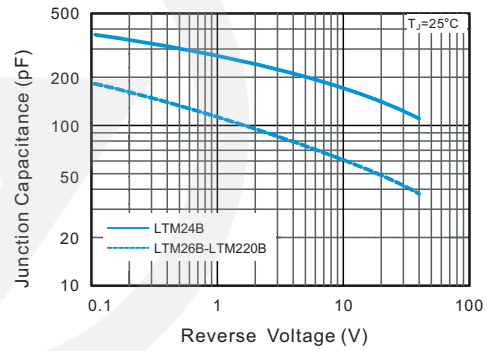


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

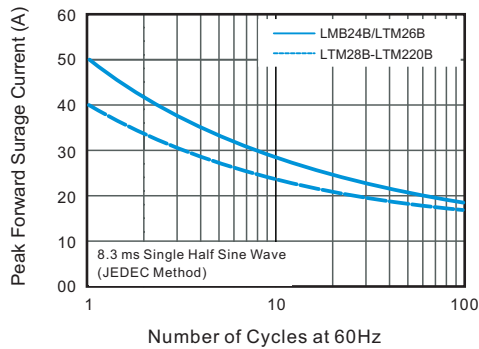
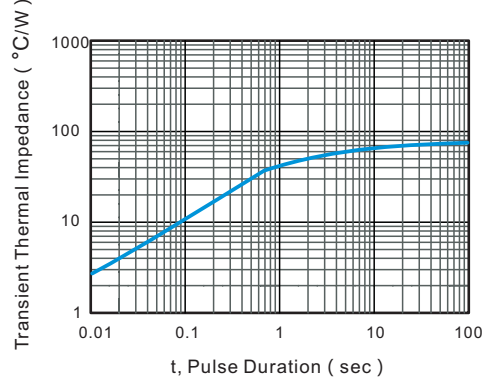
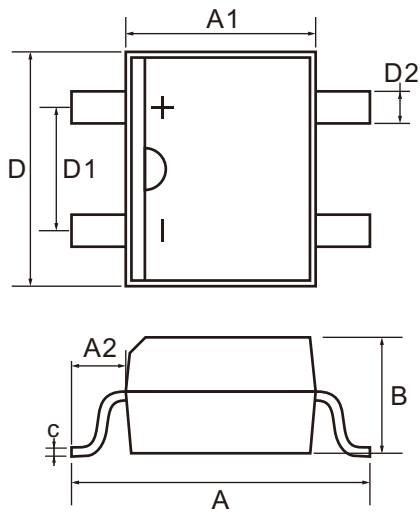


Fig.6 Typical Transient Thermal Impedance



MBS Package Outline

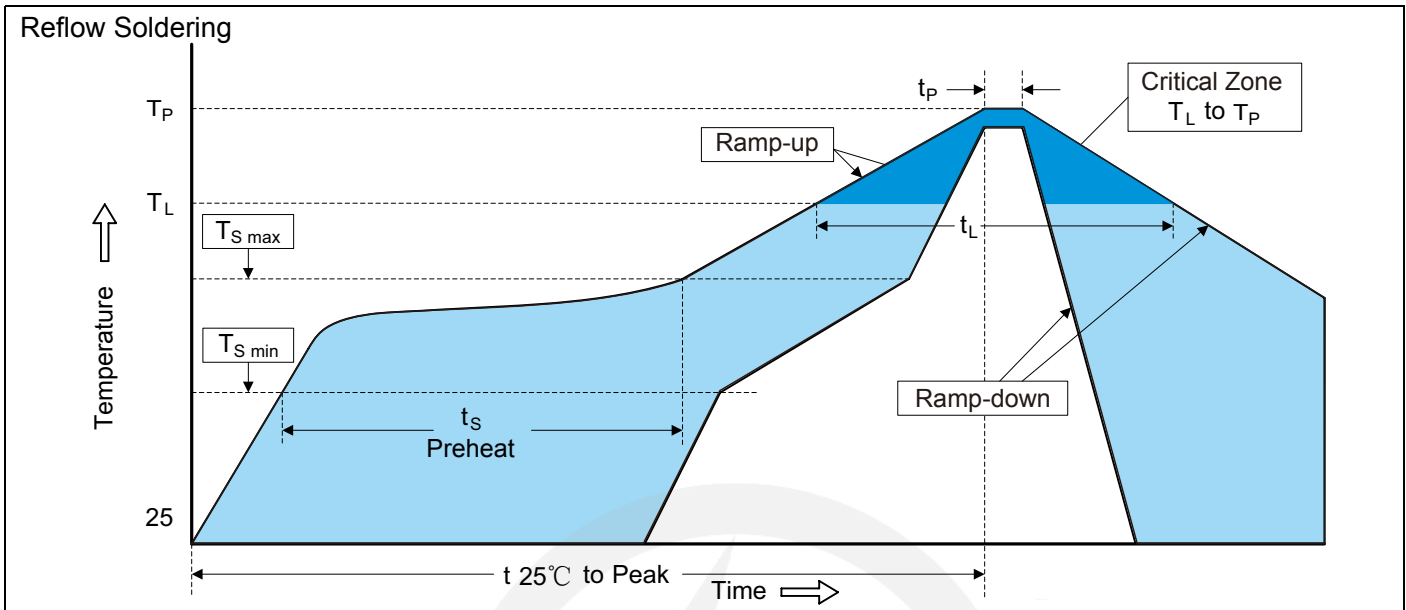


Unit: mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	6.40	7.20
A1	3.60	4.10
A2	1.30	1.70
B	2.20	2.60
D	4.50	5.00
D1	2.30	2.70
D2	0.50	0.70
C	0.15	0.25



Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat	
-Temperature Min ($T_{S\ min}$)	150°C
-Temperature Max ($T_{S\ max}$)	200°C
-Time (min to max) (t_s)	60-180 seconds
$T_{S\ max}$ to T_L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Packaging

13" Reel



D5 $\Phi 330.0 \pm 2.0$

D6 $\Phi 13.5 \pm 0.5$

H 2.5 ± 1.0

W2 16.0 ± 2.0

Quantity: 3000PCS